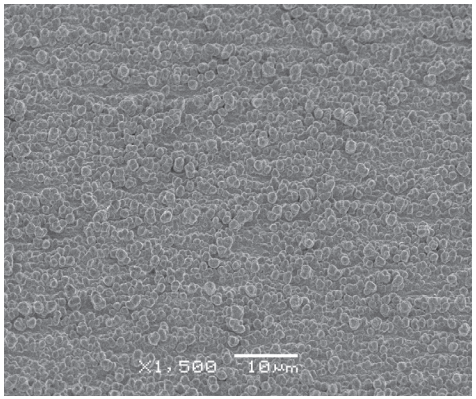
Double treat electrodeposited copper foil.

Applications:

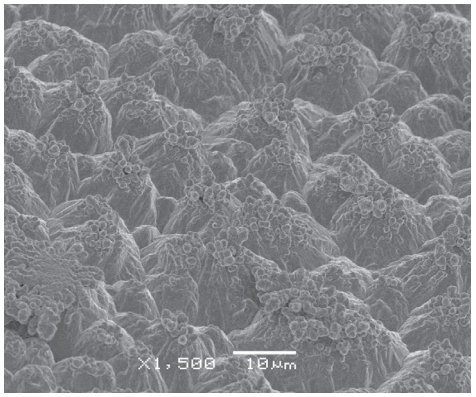
- PCB inner layers
- EMI/RF shielding in composite structures

Features:

- IPC Grade III
- Roughening treatment on both sides of the copper foil for enhanced bonding without requiring a secondary process step



Treated Drum Side
H oz. /18 μm (1500x)



Treated Matte Side
H oz. /18 μm (1500x)

Typical Values:

Attribute		Unit	Value			Reference
Thickness Designation			H	1	2	IPC-4562, 1.2.5.1 Table 1-1; IPC-TM-650-2.2.12
Nominal Thickness		μm	18	35	70	
		oz.	1/2	1	2	
Area Weight		g/m²	152.5	305	610	
		g/254 in²	25	50	100	
		oz./ft²	0.5	1	2	
Roughness	Drum Side	μm	3.05	3.05	3.05	IPC-TM-650-2.2.17
		μ"	120	120	120	
	Matte Side	μm	5.08	6.35	10.16	
		μ"	200	250	400	
Tensile	Ambient	Kg/mm²	42.2	38.7	36.9	IPC-TM-650-2.4.18
		Kpsi	60	55	52.5	
	180°C	Kg/mm²	21.1	21.1	21.1	
		Kpsi	30	30	30	
Elongation	Ambient	%	8	15	20	
	180°C	%	8	8	8	
Peel Strength* (Treated Matte Side)	Cond. B	Kg/cm	1.3	1.9	2.7	IPC-TM-650-2.4.8
		Lbs/in	7.5	10.5	15	
Peel Strength* (Drum/Treated Side)	Cond. B	Kg/cm	1.1	1.4	2.0	IPC-TM-650-2.4.8
		Lbs/in	6	8	11	

* Peel strength measured on 170°C Tg Epoxy

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